

## **ABSTRACT OF THE DISCLOSURE**

A printed-wiring substrate including a capacitor element, as well as a method for fabricating the printed-wiring substrate. An insulating substrate 3 is molded by placing a capacitor element 13 in a mold and charging a resin 4 into the mold. Therefore, the capacitor element 13 having a size (i.e., electrostatic capacitance) sufficient to suppress switching noise of an IC chip 15 and stabilize operation power voltage can be disposed, while providing a dimensional margin. Since the possibility of failing to embed the capacitor element 13 decreases, the printed-wiring substrate can be fabricated at reduced 10 cost.

DETAILED DESCRIPTION